

L Number	Hits	Search Text	DB	Time stamp
1	11214	(transfer\$3 adj mold\$3) or transfer-mold\$3	USPAT; US-PGPUB; JPO	2003/01/07 13:33
2	10870	flip-chip\$1 or (flip\$3 adj chip\$1)	USPAT; US-PGPUB; JPO	2003/01/07 13:33
3	914677	semiconduct\$3 or silicon	USPAT; US-PGPUB; JPO	2003/01/07 13:33
4	357370	bump\$3 or pad\$1	USPAT; US-PGPUB; JPO	2003/01/07 13:38
5	960500	resin or epoxy or polyimide	USPAT; US-PGPUB; JPO	2003/01/07 13:40
6	5699	((transfer\$3 adj mold\$3) or transfer-mold\$3) same (resin or epoxy or polyimide)	USPAT; US-PGPUB; JPO	2003/01/07 13:40
7	517	((((transfer\$3 adj mold\$3) or transfer-mold\$3) same (resin or epoxy or polyimide)) same (bump\$3 or pad\$1))	USPAT; US-PGPUB; JPO	2003/01/07 13:41
8	8894	((flip-chip\$1 or (flip\$3 adj chip\$1)) and (semiconduct\$3 or silicon))	USPAT; US-PGPUB; JPO	2003/01/07 13:41
9	105	(((((transfer\$3 adj mold\$3) or transfer-mold\$3) same (resin or epoxy or polyimide)) same (bump\$3 or pad\$1)) and ((flip-chip\$1 or (flip\$3 adj chip\$1)) and (semiconduct\$3 or silicon))	USPAT; US-PGPUB; JPO	2003/01/07 13:41